

5 mounting electrodes provided on the package base, to which a driving voltage is carried via conduction paths, and on which the piezoelectric resonator element is mounted, the mounting electrodes defining surfaces; and

2. The piezoelectric device according to Claim 1, the conductive anchor members including a conductive adhesive formed of a rigid resin.

4. A method for manufacturing a piezoelectric device, comprising:
bonding a piezoelectric resonator element to electrodes provided on a
package base, the bonding step including:

moving a jig in a direction substantially perpendicular to a surface of a mounting electrode, which is provided on the package base and to which a voltage is carried via a conduction path, so that the jig is brought into contact with the surface of the mounting electrode, the conductive adhesive adhered to the tip of the jig having superior adhesion to a material of the surface of the mounting electrode;

placing the piezoelectric resonator element on the anchor member provided with a silicone-based conductive adhesive thereon so as to be bonded to the anchor member.

6. The method for manufacturing a piezoelectric device according to
5 Claim 5, the adhering step including adhering conductive adhesive to the jig that is at
least one of an epoxy-based and a polyimide-based conductive adhesive.

7. The method for manufacturing a piezoelectric device according to Claim 4, the moving step including moving a jig that is a stamping jig.